

TSA-213243 1000 TO 2500 MHz, 40 WATTS HIGH POWER GaN AMPLIFIER

| Typical Values | TSA213243 |
|---|----------------------|
| Broadband | 1000-2500 MHz |
| High Saturated Power, Psat | 35-60 W, (+45.5 dBm) |
| Small Hermetic Package, 2.5"L x 2"W x 0.42"H | |

SPECIFICATIONS*

| Parameter | Guaranteed -55 to +85 °C |
|---|-----------------------------|
| Frequency (Min.) | 1000-2500 MHz |
| Small Signal Gain (Min.) | 55 dB |
| Gain Flatness (Max.) | ±1.5 dB |
| Noise Figure (Max.) | 4.0 dB |
| SWR (Max.) Input/Output | 2.0:1/2.0:1 |
| Power Output (Min.) @ 5 dB comp. | +45.5 dBm |
| DC Current (Max.) | 5A (32V), 0.45A (8V) Typ. |
| Switching Speed (Max.) 50% TTL to 90% Rise time or 10% Fall Time [^] | 100 ns Typ |

* Measured in a 50-ohm system at +32V.

[^] Faster switching speed option available upon request.

INTERMODULATION PERFORMANCE

| Typical @ 25 °C | TSA213243 |
|---|-----------|
| Second Order Harmonic Intercept Point | +82 dBm |
| Second Order Two Tone Intercept Point | +76 dBm |

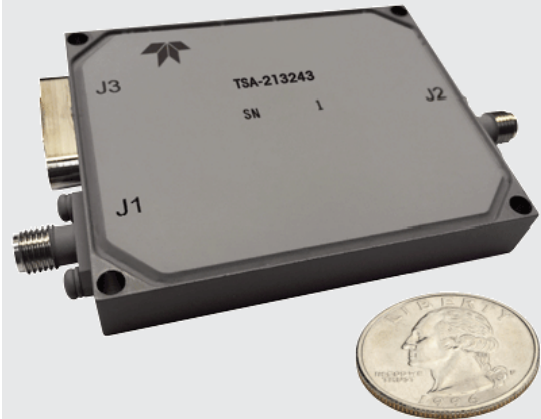
ABSOLUTE MAXIMUM RATINGS

| | |
|---|----------------|
| Storage Temperature | -62 to +125 °C |
| Maximum Case Temperature, +32V | +85 °C |
| Maximum DC Voltage | +33 Volts |
| Maximum RF Input Power | +10 dBm |
| Burn-in Temperature, +32V | +85 °C |
| Thermal Resistance ¹ (θ _{jc}) | +3 °C/Watt |
| Junction Temperature Rise Above Case (T _{jc}), +32V | +120 °C |

¹ Thermal resistance is based on total power dissipation.

TSA-213243

High Power GaN Amplifier
Band 2 Housing



HEAT SINK WARNING:

This amplifier requires an adequate heat sink to prevent damage. Maximum case temperature must not be exceeded. The package is designed to provide adequate heat transfer to proper aluminum heat sink.

The TSA-213243 amplifier provides nominal output power of 35-60 Watts. The amplifier uses control circuitry to ensure safe startup and automatic thermal shutdown and recovery. The amplifiers have an external pin for TTL on/off control. On/Off Low or High can be specified; standard is Off/Low.

Heat sinking is required to keep the case temperatures within a safe operating range. A thin layer of thermal grease or HiTherm (for example the HT-2500 series) helps provide a low resistance thermal path between the case and the mounting surface. The mounting surface should be metal with heat conduction of aluminum or better. Heat sink size depends on whether fan-driven air cooling is used, or if only convection is used.

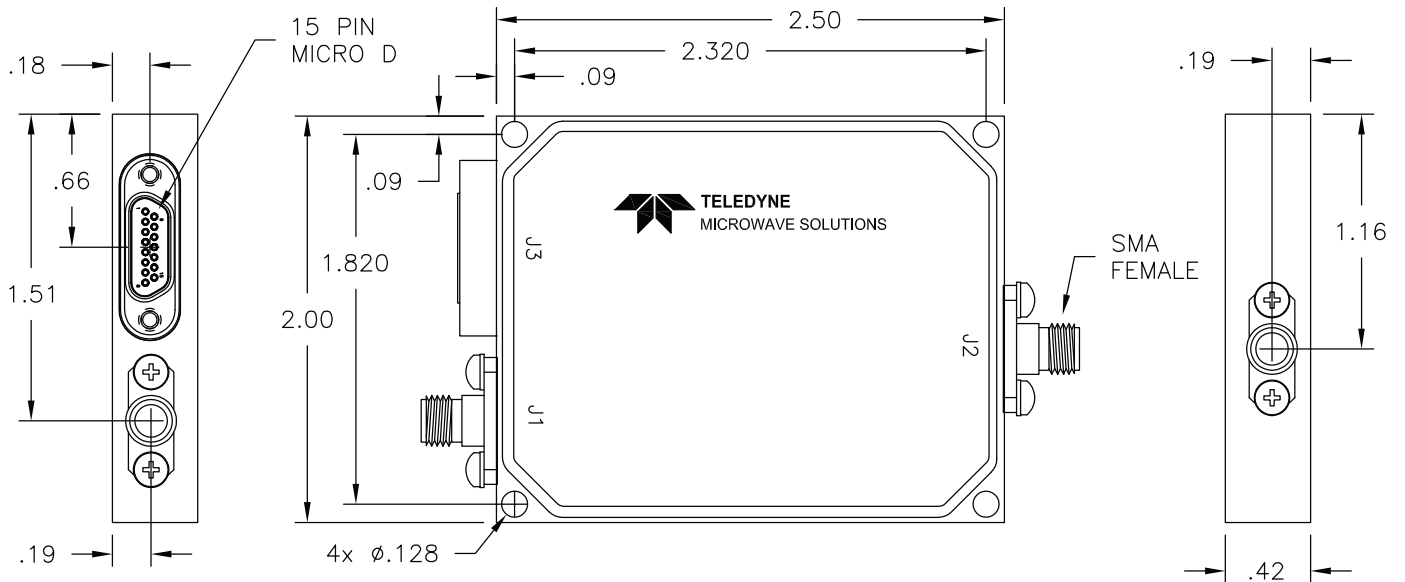
Maximum T_j of amplifier is 225°C.

LOGIC TABLE

| | |
|------|-------|
| TTL | STATE |
| HIGH | ON |
| LOW | OFF |

DIMENSIONS ARE IN INCHES (MILLIMETERS)

OUTLINE DRAWING - High Power GaN Amplifier



THIRD ANGLE PROJECTION

INCH [MM]

.XX = \pm .02 [.5]
 .XXX = \pm .010 [.25]